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CONFIRMATION NO. 3571

<b>SERIAL NUMBER</b> 10/771,990	<b>FILING OR 371(c) DATE</b> 02/03/2004 <b>RULE</b>	<b>CLASS</b> 228	<b>GROUP ART UNIT</b> 1725	<b>ATTORNEY DOCKET NO.</b> 09450/100K673-US2
<b>APPLICANTS</b> Masahiko Furuno, Saitama, JAPAN; Tsugunori Masuda, Saitama, JAPAN; Hideo Aoki, Yokohama, JAPAN; Kazuhide Doi, Mie, JAPAN;				
<b>** CONTINUING DATA *****</b> <i>AM</i> This application is a DIV of 10/161,566 05/30/2002 PAT 6,742,701 which is a CIP of 09/554,651 09/27/2000 ABN <i>AM</i> which is a 371 of PCT/JP99/01956 04/13/1999 <i>AM</i>				
<b>** FOREIGN APPLICATIONS *****</b> JAPAN 1998/262195 09/17/1998 <i>AM</i>				
<b>IF REQUIRED, FOREIGN FILING LICENSE GRANTED</b> <b>** 05/11/2004</b>				
Foreign Priority claimed <input checked="" type="checkbox"/> yes <input type="checkbox"/> no 35 USC 119 (a-d) conditions <input checked="" type="checkbox"/> yes <input type="checkbox"/> no <input type="checkbox"/> Met after met Verified and Acknowledged <i>AM</i> Examiner's Signature Initials	<b>STATE OR COUNTRY</b> JAPAN	<b>SHEETS DRAWING</b> 19	<b>TOTAL CLAIMS</b> 23	<b>INDEPENDENT CLAIMS</b> 5
<b>ADDRESS</b> 7278				
<b>TITLE</b> Bump forming method, presoldering treatment method, soldering method, bump forming apparatus, presoldering treatment device and soldering apparatus				
<b>FILING FEE RECEIVED</b> 996	FEES: Authority has been given in Paper No. _____ to charge/credit DEPOSIT ACCOUNT No. _____ for following:			
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